



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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## Ground Blocks

Combining advanced materials with an elegant design, Amphenol Pcd's Ground Blocks provide the lightest weight, highest density grounding solution available in the market today. Wired connections are environmentally-sealed, providing protection from moisture, spray, and debris. Unused connections are protected via Amphenol Pcd's patented FODSeal Technology, which replaces the sealing plugs - reducing FOD, weight and part count. Amphenol Pcd's Ground Blocks are ideal for use in harsh environments typically found in aircraft, ground vehicle and naval applications.



## Features & Benefits

### *Overmold Technology*

Simplifies construction and improves sealing and reliability

### *Plastic retention clip - made with VICTREX® PEEK Polymer*

Simplifies construction; uses 1 plastic piece vs 6 individual metal pieces

### *FODSeal Technology (Patented)*

Reduces FOD, part count and weight by eliminating sealing plugs

### *Smart Engineering*

Weight Savings - up to 0.06 oz per block vs standard designs, yielding up to 2lbs per plane on typical aircraft

## Part Numbers

Part Number	With/Without Contacts	Number of Contacts	Contact Size	Boeing P/N
BDX016016-2	Without	12	16	BACC50AN16H
BDX016017-2	With			BACC50AN16
BDX016020-2	Without	16	20	BACC50AN20H
BDX016021-2	With			BACC50AN20

# Materials

## Web Membrane

Silicone per A-A-59588, class 2B, 40 durometer. color clear

## Grommet

Silicone per A-A-59588, class 2B, 40 durometer. color grey

## Housing

Glass reinforced polyamide; color red (size 20), blue (size 16)

## Internal Contacts

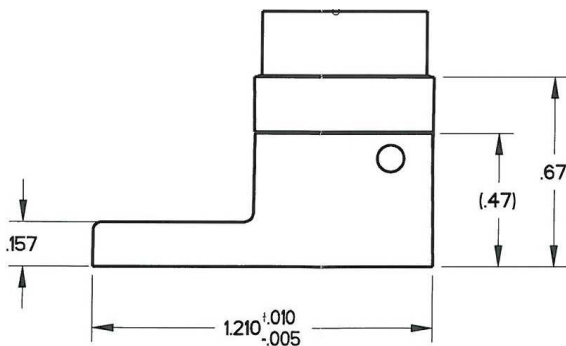
BeCu C17410, gold per MIL-DTL-45204, Type II, grade C, class I, over nickel per SAE-AMS-QQ-N-290, class I

## Base

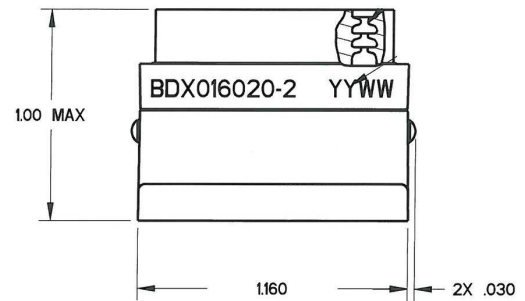
Aluminum A380.0. chromate conversion per MIL-DTL-81706, type I, class IA, method C

# Ground Block Dimensions

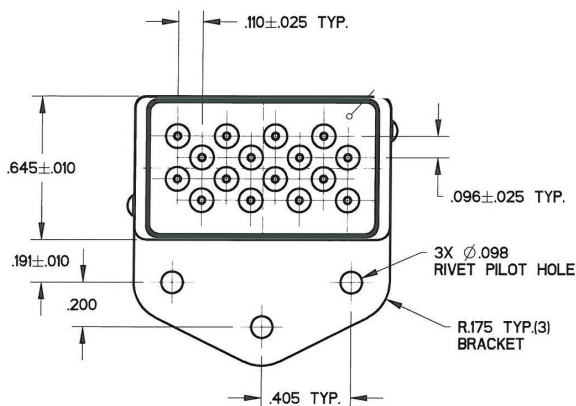
## SIDE VIEW



## FRONT VIEW



## TOP VIEW SIZE 20



## TOP VIEW SIZE 16

